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**TITLE:** ADHESIVE COMPOSITION  
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**INVENTOR-INFORMATION:**

NAME	COUNTRY
SAKUYAMA, HIROSHI	
KOU, REISHIYUU	
HAYASHI, MASAZOE	

**ASSIGNEE-INFORMATION:**

NAME	COUNTRY
NIPPON MEKTRON LTD	N/A

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**ABSTRACT:**

**PROBLEM TO BE SOLVED:** To obtain the subject composition capable of improving adhesiveness under a room

temperature condition, useful for bonding flexible printed board, by using a siloxane polyimide soluble in an organic solvent of general purpose as an adhesive component.

**SOLUTION:** This composition comprises (A) a siloxane polyimide composed of a copolymer of (i) a diaminopolysiloxane-alcyclic diamine mixture and (ii) an aromatic tetracarboxylic acid dianhydride, (B) an epoxy resin, (C) a diamine- based curing agent, (D) a fluorine surfactant and (E) an organic solvent. For example, a reaction product of a compound of the formula (R is a 2-6C bifunctional hydrocarbon; R1 to R4 are each a 1-5C alkyl or phenyl; (n) is 0-30), etc., and 1,3-bis(aminomethyl)cyclohexane, etc., is preferably used as the component (i).

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